IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: FUKASAWA, et al.

Serial No.: 09/766,656

Filed: January 23, 20

Group Art Unit: 2814

Prior Examiner: D. Graybill

P.T.O. Confirmation No.: 1144

FOR: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR

DEVICE, AND METHOD FOR MOUNTING THE DEVICE

AMENDMENT TRANSMITTAL

Commissioner for Patents Washington, D.C. 20231

November 26, 2002

Sir:

Transmitted herewith is an Amendment in the above-identified application. The fee has been calculated as shown below:

	CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims	23	20	_ =	3	X \$9	X \$18	54.00
independent Claims	6	8	=_	0	X \$42	X \$84	0
First Presentation of Multiple Dependent Claims \$140 280							
TOTAL FEES ENCLOSED:							\$54.00

- XX Enclosed please find our check in the amount of \$54.00 for the additional claims fee in connection with this amendment.
- XX The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. <u>01-2340</u>. Two duplicates of this sheet are attached.

Respectfully submitted,

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SGA/arf

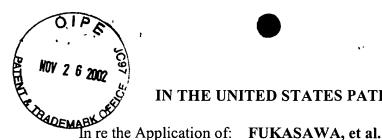
Atty. Docket No. **980233B** Suite 1000, 1725 K Street, N.W. Washington, D.C. 20006 (202) 659-2930



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814

Serial No.: 09/766,656

Prior Examiner: D. Graybill

Filed: January 23, 2001

P.T.O. Confirmation No.: 1144

For.

METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE, SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE

SECOND SUPPLEMENTAL PRELIMINARY AMENDMENT

Commissioner for Patents Washington, D.C. 20231

Date: November 26, 2002

Sir:

Further to the Supplemental Preliminary Amendment filed February 21, 2002, please amend the above-captioned patent application as follows:

IN THE CLAIMS:

Please add new claims 111-120 as follows:

111. A method for fabricating a semiconductor device comprising:

a resin sealing step of loading a wiring board having a flexible member on which a semiconductor element and leads are arranged onto a mold and supplying sealing resin to the semiconductor element so as to seal the semiconductor element; and

0)

a protruding electrode forming step of forming protruding electrodes so as to be